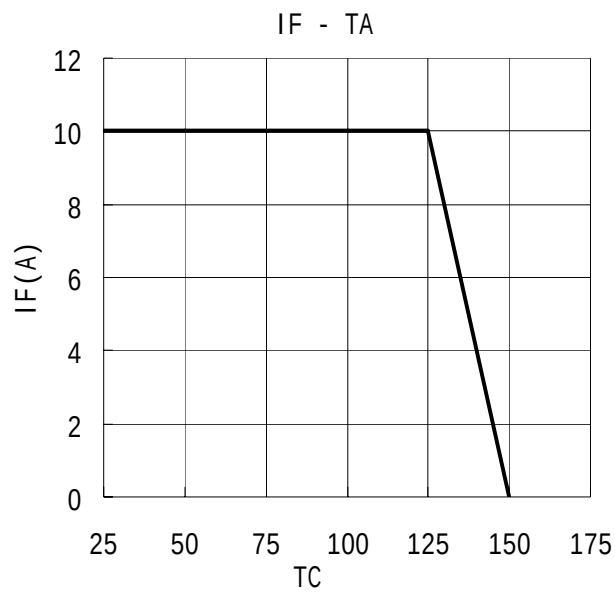
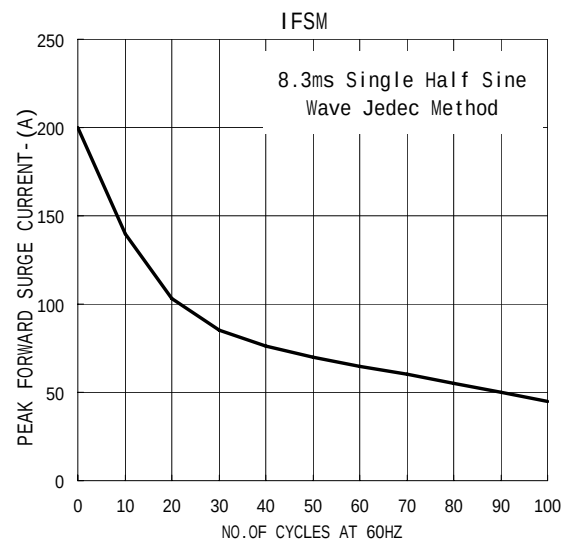
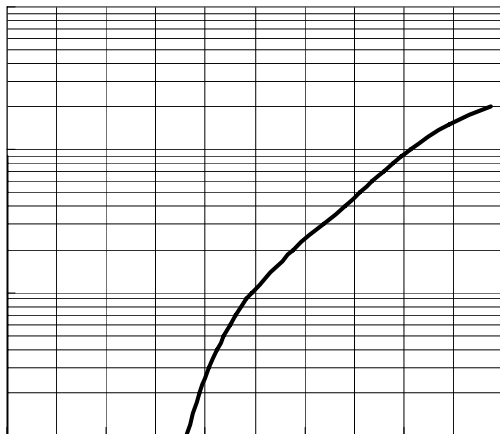




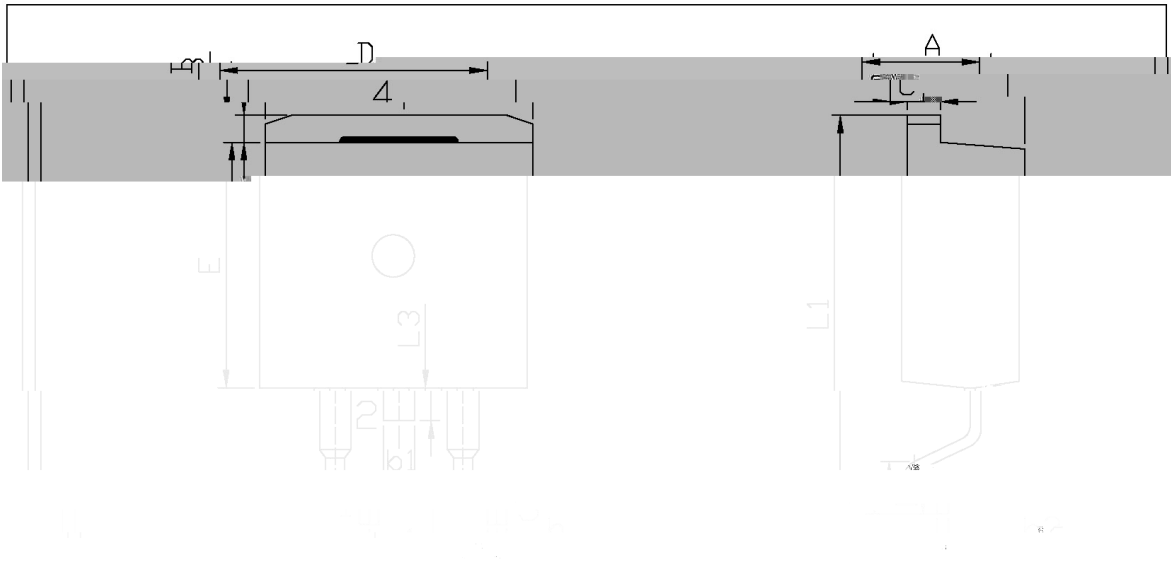
Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RM} V_{RSM} V_{DC}	150	V
RMS Reverse Voltage	V_{RMS}	105	V
Average forward rectified current	$I_{F(AV)}$	1×10	A
Non Repetitive Peak Surge Current	I_{FSM}	200	A
Thermal Resistance Junction to Case	R_{JC}	2.8	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40 +150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{(BR)R}$	$I_R=1mA(T_a=25^\circ C)$	150			V
Forward Voltage	V_F	$I_F=2A(T_a=25^\circ C)$		0.58		V
		$I_F=10A(T_a=25^\circ C)$		0.81	0.85	V
		$I_F=2A(T_a=125^\circ C)$		0.47		V
		$I_F=10A(T_a=125^\circ C)$		0.69	75	V

/ Electrical Characteristic Curve

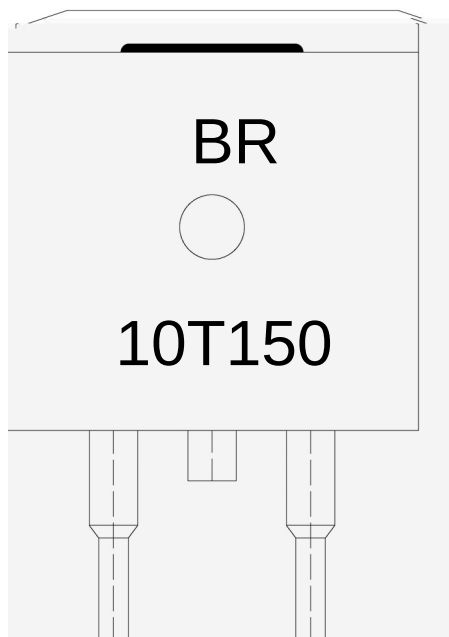


/ Package Dimensions



Max		Min		Max		Min	
9.40		A		4.30		4.70	
2.74		B		1.00		1.40	
4.28	3.26	b1		1.15	1.35	L1	
15.00	16.00	b2		0.40	0.60	L2	
2.24	2.84	C		1.20	1.40	L3	
1.20	1.60	D		9.30	10.20		
		T.1-263					

/ Marking Instructions



公司代码

BR

43W483

Note:

BR:

10T150

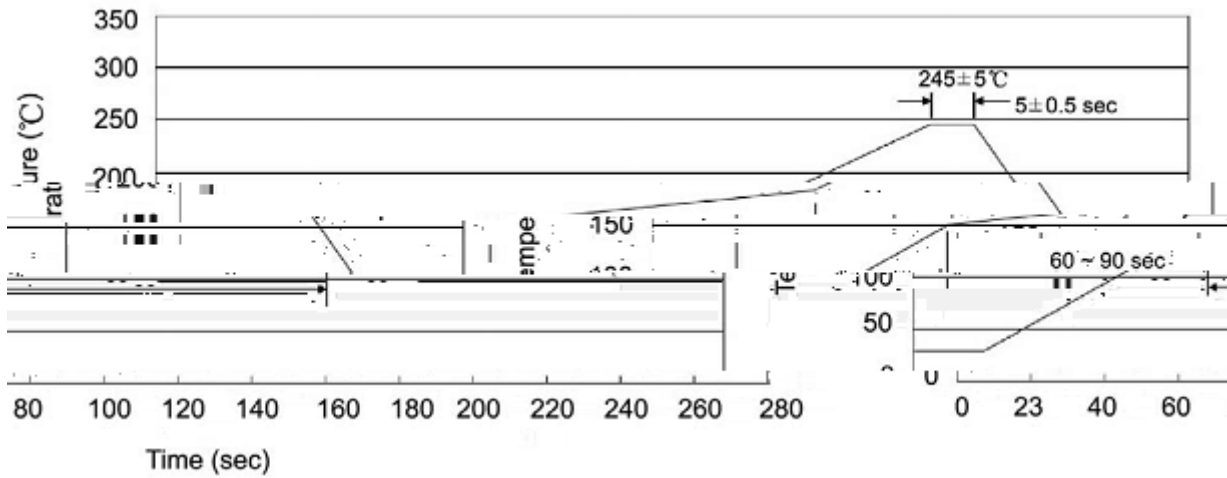
公司代码

43W483

Company Code

Product Type.

Lot No. Code, code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)


℃

1. 预加热: 25~150℃, 时间: 60~90sec;
2. 峰值温度: 245±5℃, 峰值时间: 5±0.5sec;
3. 冷却速度: 2~10℃/sec.

Note:

1. Preheating: 25~150℃, Time: 60~90sec.
2. Peak Temp.: 245±5℃, Duration: 5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

□ 预加热: 260±5℃, 时间: 10±1 sec. Temp.: 260±5 Time: 10±1 sec

/ Packaging SPEC.

□ 卷带 / REEL

Package Type	Units					Dimension (unit mm ³)		

□ 管装 / TUBE

Package Type	Units					Dimension (unit mm ³)		

/ Notices